

ECCOBOND[®] 55 Unfilled, General Purpose Epoxy Adhesive

| Key Feature: | Benefit: | | |
|--|---|--|--|
| General purpose | Bonds well to metal, glass and plastic substrates | | |
| Low viscosity | Ease of dispensing and use | | |
| Variety of catalysts available | Versatility of resin system | | |

Product Description:

ECCOBOND 55 is an unfilled, low viscosity, general purpose epoxy adhesive resin that can be cured with a variety of catalysts. It features good wetting of most substrates and offers good chemical, solvent and water resistance. ECCOBOND 55 bonds well to glass, ceramics, metals and plastics.

Applications:

ECCOBOND 55 is designed for electronic component assembly, staking of adjustment and calibration screws, anchoring of inserts, end fills or hermetic sealing.

Instructions For Use:

Thoroughly read the information concerning health and safety contained in this bulletin before using. Observe all precautionary statements that appear on the product label and/or contained in individual Material Safety Data Sheets (MSDS). To ensure the long term performance of the bonded assembly, complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt, and oils which can cause poor adhesion or corrosion in a bonded part. For information on proper substrate preparation, refer to the reprint "Good Adhesive Bonding Starts With Surface Preparation" available from Emerson & Cuming.

Some separation of components is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use. Power mixing is preferred to ensure a homogeneous product.

Accurately weigh resin and hardener into a clean container in the recommended ratio. Weighing apparatus having an accuracy in proportion to the amounts being weighed should be used.

Blend components by hand, using a kneading motion, for 2-3 minutes. Scrape the bottom and sides of the mixing container frequently to produce a uniform mixture. If possible, power mix for an additional 2-3 minutes. Avoid high mixing speeds which could entrap excessive amounts of air or cause overheating of the mixture resulting in reduced working life.

Apply the adhesive to all surfaces to be bonded and join together. In most applications only contact pressure is required.

Properties of Material As Supplied:

| Property | Test Method Unit | | Value | | | |
|----------------------|------------------|-------------------|--------------------|--|--|--|
| Chemical Type | | | Ероху | | | |
| Appearance | Visual | | Milky White Liquid | | | |
| Density | ASTM-D-792 | g/cm ³ | 1.18 | | | |
| Brookfield Viscosity | ASTM-D-2393 | Pa.s | 16 | | | |
| | | cP | 16,000 | | | |

| Choice of Curing Agents | | | | | | | |
|-------------------------|---|----------------|---|---|--|--|--|
| Curing agent | | Catalyst 9 | Catalyst 11 | Catalyst 23 LV | | | |
| Description | n General purpose with good chemical resistance and physical strength. Chemical properties at eleva temperatures. | | Long pot life, excellent chemical resistance, good physical and chemical properties at elevated temperatures. | Low color, low viscosity, long pot life. Excellent, thermal shock and impact resistance. Excellent low temperature properties and adhesion to glass. | | | |
| Type of cure | | Room | Heat | Room | | | |
| Viscosity | Pa.s | 0.080 to 0.105 | 0.035 to 0.060 @ 65 °C | 0.020 to 0.030 | | | |
| | сP | 80 to 105 | 35 to 60 @ 65 °C | 20 to 30 | | | |

Properties of Material As Mixed:

| Property | Test Method | Unit | Value | | |
|--|-------------|-------------------|------------|-------------|----------------|
| | | | Catalyst 9 | Catalyst 11 | Catalyst 23 LV |
| Mix Ratio - Amount of Catalyst per 100 | By Weight | 13.5 | 16 | 28 | |
| 55 | By Volume | 15.5 | 17 | 32 | |
| Working Life (100 g @ 25°C) | ERF 13-70 | | 45 minutes | >4 hours | 60 minutes |
| Density | ASTM-D-792 | g/cm ³ | 1.14 | 1.15 | 1.12 |
| Brookfield Viscosity | ASTM-D-2393 | Pa.s | 8 | 7.1 | 3.3 |
| | | cP | 8,000 | 7,100 | 3,300 |

"Our service engineers are available to help purchasers obtain best results from our products, and recommendations are based on tests and information believed to be reliable. However, we have no control over the conditions under which our products are transported to, stored, handled, or used by purchasers and, in any event, all recommendations and sales are made on condition that we will not be held liable for any damages resulting from their use. No representative of ours has any authority to waive or change this provision. We also expect purchasers to use our products in accordance with the guiding principles of the Chemical Manufacturers Association's Responsible Care® program."

Cure Schedule:

Cure at any one of the recommended cure schedules. For optimum performance, follow the initial cure with a post cure of 2-4 hours at the highest expected use temperature. Alternate cure schedules may also be possible. Contact your Emerson & Cuming Specialty Polymers Technical Representative for further information.

| Temperature | Cure Time | | | | |
|-------------|---------------|----------------|-------------------|--|--|
| °C | Catalyst 9 | Catalyst 11 | Catalyst 23 LV | | |
| 25 | 16-24 hrs | | 24 hrs | | |
| 45 | 4-6 hrs | | 4-6 hrs | | |
| 65 | 1-2 hrs | | 2-4 hrs | | |
| 80 | | 8-16 hrs | | | |
| 100 | | 2-4 hrs | | | |
| 120 | | 30-60 min | | | |

Properties of Material After Application:

| Property | Test Method | Unit | Value | | |
|----------------------------------|-------------|----------------------|-------------------|-------------|----------------|
| | | | Catalyst 9 | Catalyst 11 | Catalyst 23 LV |
| Flexural Strength | ASTM-D-790 | mPa | 100 | | |
| | | psi | 14,500 | | |
| Tensile Lap Shear Strength | ASTM D-1002 | mPa | 12.4 | | |
| aluminum to aluminum @ 25°C | | psi | 1,700 | | |
| Coefficient of Thermal Expansion | ASTM-D-3386 | 10⁻ ⁶ /°C | 59 | | |
| Temperature Range of Use | | °C | -40 to + 130 | -55 to +155 | -65 to +105 |
| Outgassing ⁽¹⁾ | ASTM-E-595 | | | | |
| TML | | % | 0.45 | | |
| CVCM | | % | 0.02 | | |
| Dielectric Strength | ASTM-D-149 | kV/mm | 17 | | |
| | | V/mil | 440 | | |
| Dielectric Constant @ 1 mHz | ASTM-D-150 | - | 3.3 | | |
| Dissipation Factor @ 1 mHz | ASTM-D-150 | - | 0.02 | | |
| Volume Resistivity | ASTM-D-257 | | | | |
| @ 25°C | | Ohm-cm | >10 ¹⁵ | | |
| @ 93°C | | Ohm-cm | >10 ¹¹ | | |

⁽¹⁾ per NASA Reference Publication 1124. Sample tested was cured for 0.5 hours @ 66°C.

Storage and Handling:

The shelf life of ECCOBOND 55 is 12 months at 25°C. For best results, store in original, tightly covered containers. Storage in cool, clean and dry areas is recommended. Usable shelf life may vary depending on method of application and storage conditions.

Health and Safety:

The ECCOBOND 55, like most epoxy compounds, possesses the ability to cause skin and eye irritation upon contact. Certain individuals may also develop an allergic reaction after exposure (skin contact, inhalation of vapors, etc.) which may manifest itself in a number of ways including skin rashes and an itching sensation. Handling this product at elevated temperatures may also generate vapors irritating to the respiratory system.

Good industrial hygiene and safety practices should be followed when handling this product. Proper eye

protection and appropriate chemical resistant clothing should be worn to minimize direct contact. Consult the Material Safety Data Sheet (MSDS) for detailed recommendations on the use of engineering controls and personal protective equipment.

This information is only a brief summary of the available safety and health data. Thoroughly review the MSDS for more complete information before using this product.

Attention Specification Writers:

The values contained herein are considered typical properties only and are not intended to be used as specification limits. For assistance in preparing specifications, please contact Emerson & Cuming Quality Assurance for further details.

Medical Implantable Disclaimer

"In the event this product is intended by you for use in implantation in the human body, you are hereby advised that National Starch (or Emerson & Cuming) has not performed clinical testing of these materials for implantation in the human body nor has National Starch (Emerson & Cuming) sought, nor received, approval from the FDA for the use of these material in implantation in the human body. It is YOUR responsibility, as a manufacturer of any such device, to ensure that all materials and processes relating to the manufacture of any medical device fully comply with all applicable federal, state and local laws, rules, regulations and requirements as well as any such laws, rules, regulations, directives or other orders of any foreign country where such product is sold. If you have not undertaken the necessary investigations to ensure compliance you are advised NOT TO USE this product in the manufacture of any device which is to be implanted in the human body. No representative of ours has any authority to change the foregoing provisions."



Underfills Solder Alternatives C.O.B Materials Encapsulants Coatings Adhesives Film Adhesives Thermal Interfaces Electrically Conductive Coatings and Adhesives

✓ Europe
 Nijverheidsstraat 7
 B-2260 Westerlo
 Belguim
 ■ : +(32)-(0) 14 57 56 11
 Fax: +(32)-(0) 14 58 55 30

North America
 46 Manning Road
 Billerica, MA 01821
 978-436-9700
 Fax : 978-436-9701

▲ Asia-Pacific 100 Kaneda, Atsugi-shi Kanagawa-ken, 243-0807 Japan ■ : (81) 46-225-8815 Fax: (81) 46-222-1347